

## REMARKS/ARGUMENTS

The Office Action mailed June 4, 2003 has been reviewed and carefully considered. Claim 12 is added. Claims 1-12 are pending in this application, with claims 1, 7, and 12 being the only independent claims. Reconsideration of the above-identified application, as herein amended and in view of the following remarks, is respectfully requested.

In the Office Action mailed June 4, 2003, claims 1-11 stand rejected under 35 U.S.C. §102(b) as anticipated by U.S. Patent No. 5,821,836 (Katehi).

Claims 1-11 stand rejected under 35 U.S.C. §102(b) as anticipated by U.S. Patent No. 6,170,154 (Swarup).

Before discussing the cited prior art and the Examiner's rejections of the claims in view of that art, a brief summary of the present invention is appropriate. The present invention relates to a structure for separating incoming high-frequency energy to its own path or combining different paths to a common path. Examples of high-frequency dividing means include power dividers and directional couplers. The present invention includes a handling means for high-frequency energy including a dielectric board having at least two strip conductors. At least one hole in the dielectric board is filled with conductive material. In one embodiment, the handling means further comprises at least one resistive structural part. In another embodiment, an electromagnetic coupling is arranged between the at least two strip conductors.

Katehi discloses a miniaturized filter assembly including a microresonator. The Examiner states that the metallized surface 102 of cavities 86, 87, 88 discloses the claimed hole filled with conductive material. However, the structural part 102 is only a metallized coating and is not a hole filled with conductive material, as recited in independent claim 1.

Furthermore, the Examiner states that layer 78 is a resistive structural part. However, the layer 78 is described in col. 4, line 46 as a metal layer. It is respectfully submitted that a metal layer such as layer 78 can not be considered to be a resistive layer as recited in independent claims 1 and 7. Rather, the layer 48 is a conductive element instead of a resistive element.

Accordingly, it is respectfully submitted that Katehi fails to disclose "at least two strip conductors, between which there is a coupling", "at least one hole filled with conductive material", and "at least one resistive structural part", as recited in independent claim 1.

Since Katehi discloses a resonator, Katehi also fails to disclose "at least two strip conductors, between which there is an electromagnetic coupling" and "at least two conductors of said strip conductors are located in different interlayers of the multilayer board on top of each other to arrange said electromagnetic coupling", as recited in independent claim 7.

Accordingly, claims 1 and 7 are not anticipated by Katehi.

Swarup discloses a circuit packaging structure including lumped elements. Swarup discloses the use of vias in col. 7, lines 48-49 but fails to teach or suggest that the vias are filled with a conductive material. Accordingly, Swarup fails to disclose the hole filled with conductive material as recited in independent claim 1. The Examiner refers to Figs. 3A and 3B of Swarup. These Figs. of Swarup show a spiral inductor 60. The Examiner states that the dielectric bridge 70 is the claimed resistive structural part. However, the dielectric bridge 70 is arranged to conduct a signal from the inductor 64 to an output part 74 (col. 7, lines 46-48). Accordingly, the dielectric bridge 70 can not be considered a resistive structural part as recited in the claims. Since independent claim 1 recites both conductors and a resistive structural part, the

dielectric bridge 70 for conducting the signal must be considered to be a conductive element. Accordingly, Swarup fails to disclose a resistive structural part as recited in independent claim 1.

Regarding claim 7, Swarup discloses circuits shown in Figs. 1 and 2. These circuits of Swarup are completely devoid of any electromagnetic couplings. Accordingly Swarup fails to disclose "at least two strip conductors, between which there is an electromagnetic coupling" and "at least two conductors of said strip conductors are located in different interlayers of the multilayer board on top of each other to arrange said electromagnetic coupling", as recited in independent claim 7.

Dependent claims 2-6 and 8-11, each being dependent on one of independent claims 1 and 7, are allowable for at least the same reasons as independent claims 1 and 7.

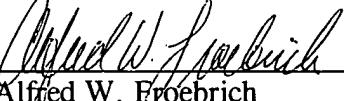
New independent claim 12 is added to more specifically recite limitations drawn to the structure disclosed in Figs. 3a, 3b, 4a, and 4b.

The application is now deemed to be in condition for allowance and notice to that effect is solicited.

Respectfully submitted,

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